

Advanced Modeling of DR Vacuum Chamber Components

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Outline

- *EM Modeling Focus Areas*
- *Parallel Finite Element EM Codes/MAFIA*
- *Applications to Beamline Components*

Electromagnetic Modeling Focus Areas

Design and Evaluate the damping ring vacuum chamber

- **Broadband Impedance** – Obtain the broadband impedance from calculating the short-range wakefields of major beamline components: RF cavity, BPM, bellows, pumping slots, tapers and collimators etc.
- **Narrowband Impedance** – Design for the damping of dangerous modes in RF cavity and BPM to ensure the DR meets beam stability requirements.
- **Beam Heating** – Identify beam excited trapped modes in the RF cavity and bellows for design modification to avoid excessive heating.
- **Device Performance** – Determine the signal sensitivity of pickup devices such as BPMs and kickers.



Outline

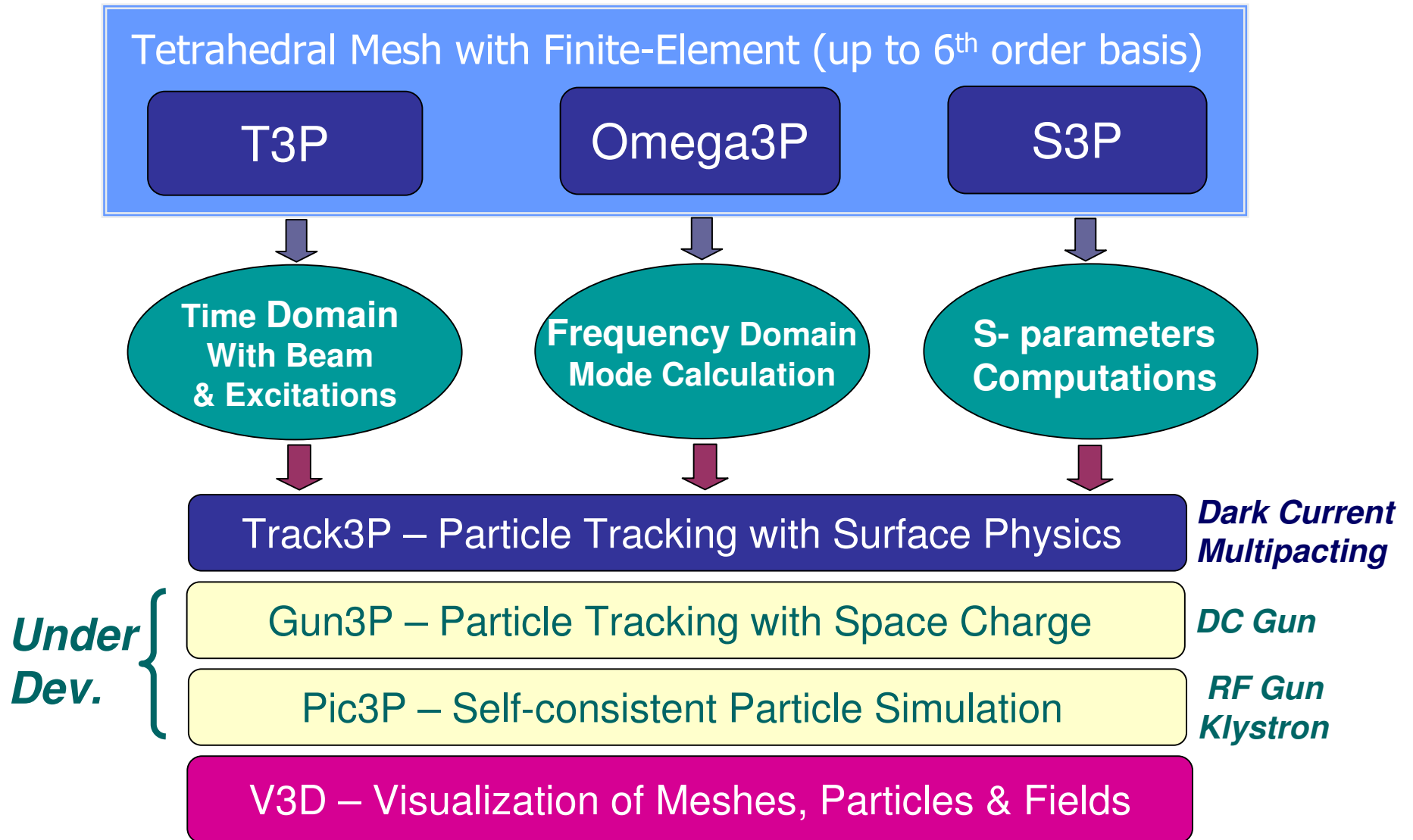
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SciDAC Computational Tools

- **SLAC's Parallel Finite Element EM** codes provide higher accuracy than standard software (e.g. **MAFIA**) and can simulate LARGE problems to high resolution with near linear speedup through petascale computing (NERSC, NCCS):
- **Omega3P** – nonlinear eigensolver to find resonant modes in damped RF cavities.
- **S3P** – frequency domain solver to compute the scattering matrix of RF structures.
- **T3P** – time domain solver to calculate transients due to external drive and wakefield generated by beam transit.
(Under development includes indirect wakefield integration for collimator-type structures, and surface impedance BC to model resistive wall wakefields of grooved vacuum chamber).



SLAC 3D Parallel FEM EM Codes

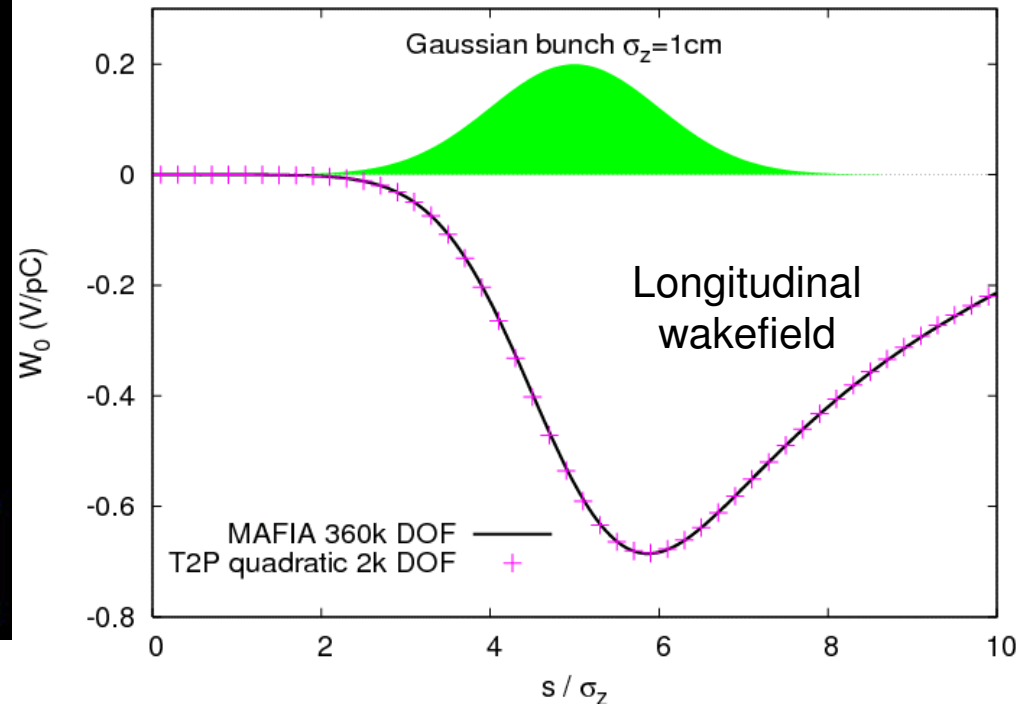
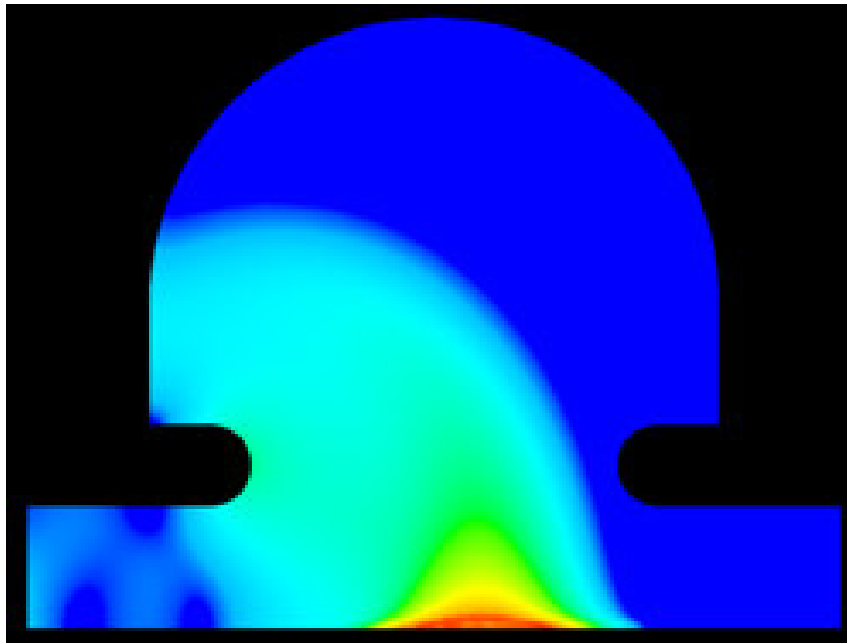


Programmed in C++ & MPI



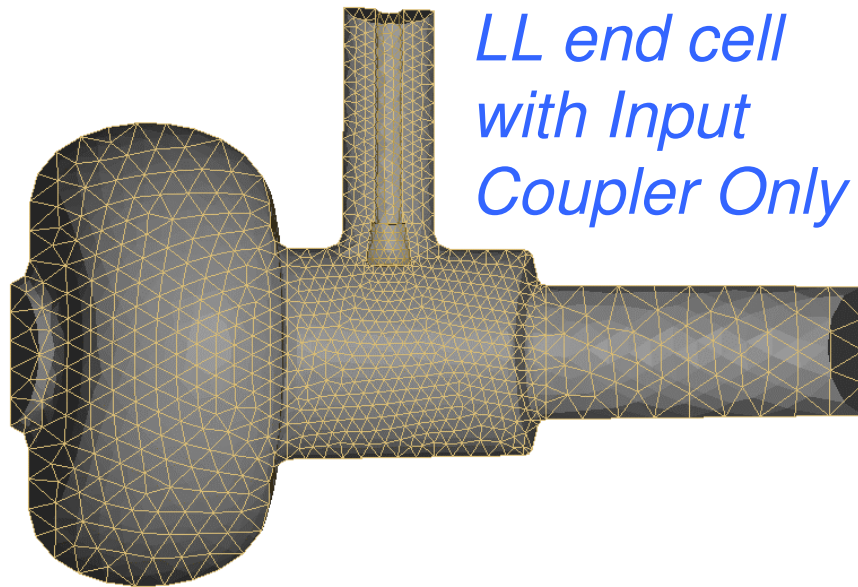
FEM Wakefield Computation

Wakefield Benchmark (2D)

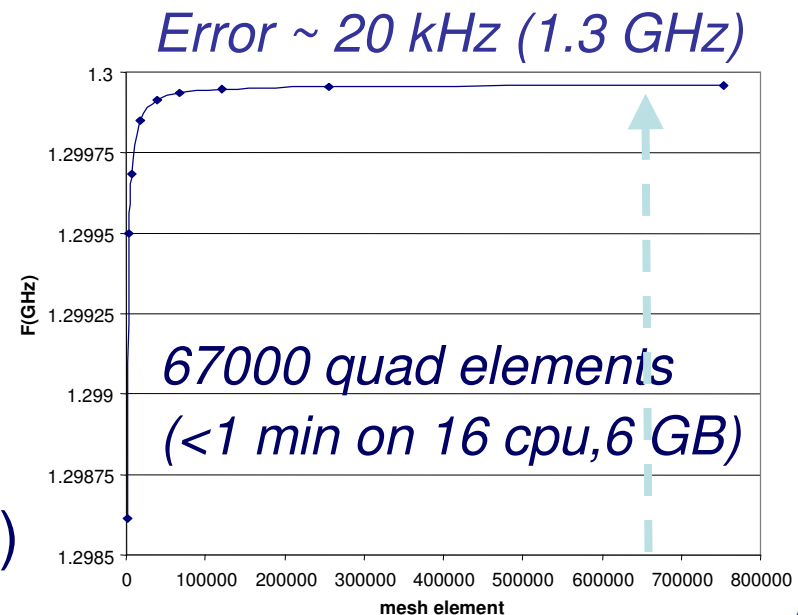
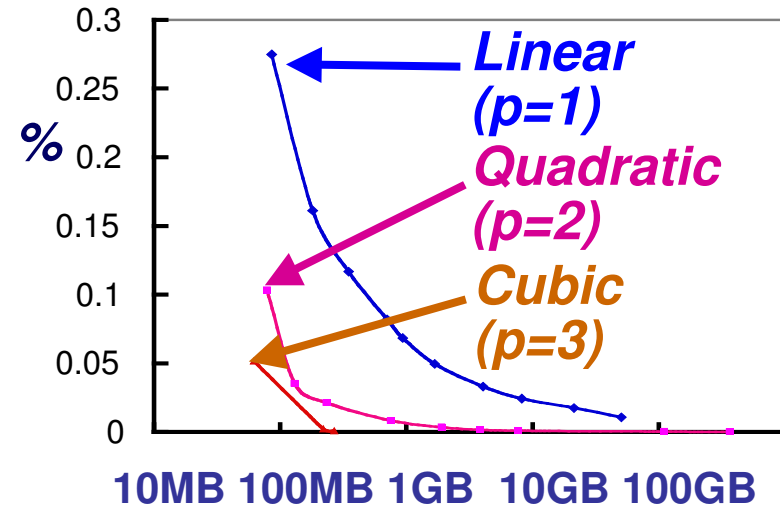


Quadratic elements achieve convergence with far less DOFs than possible with structured grid (2k vs 360k).

Higher-order FEM + Parallel Processing



- Tetrahedral Conformal Mesh w/ quadratic surface
- Higher-order Finite Elements ($p = 1-6$)
- Parallel Processing (large memory & $1/N$ speedup)



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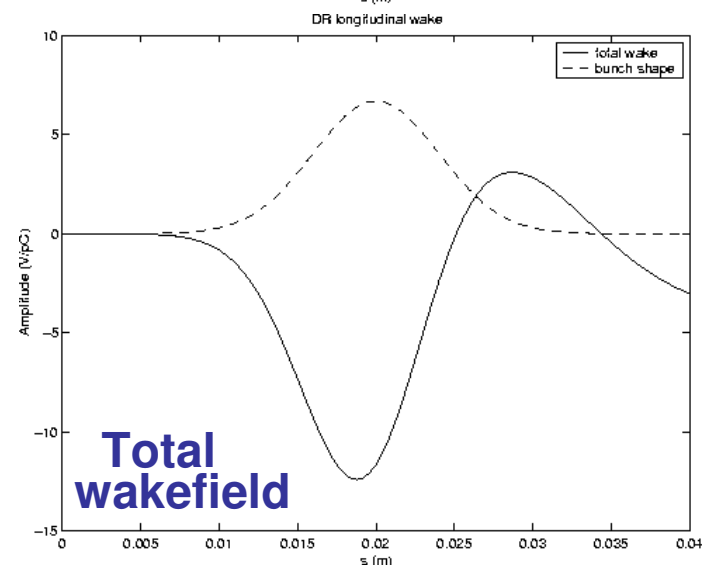
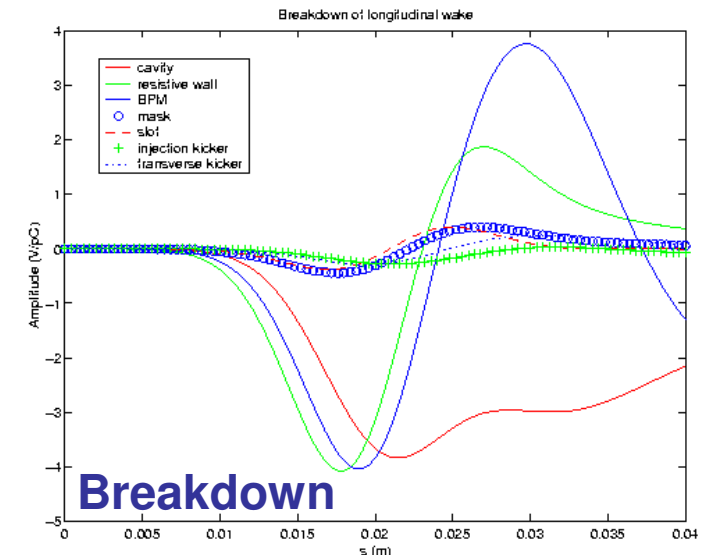
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NLC-DR Longitudinal Broadband Impedance

Impedance budget

| Component | Quantity | Loss factor (V/pC) | Inductance (nH) |
|-------------------|----------|--------------------|-----------------|
| RF Cavity | 3 | 2.976 | 0.41 |
| BPM | 159 | 2.226 | 2.97 |
| Slot | 102 | 0.068 | 0.28 |
| Mask | 102 | 0.168 | 0.33 |
| Injection kicker | 2 | 0.192 | 0.21 |
| Transverse kicker | 2 | 0.171 | 0.21 |
| Resistive wall | | 1.867 | |
| Total | | 7.7 | 4.4 |

- c.f. PEP-II HER ring:
Loss factor = 2.5 V/pC
Inductance = 48 nH



NLC-DR Transverse Broadband Impedance

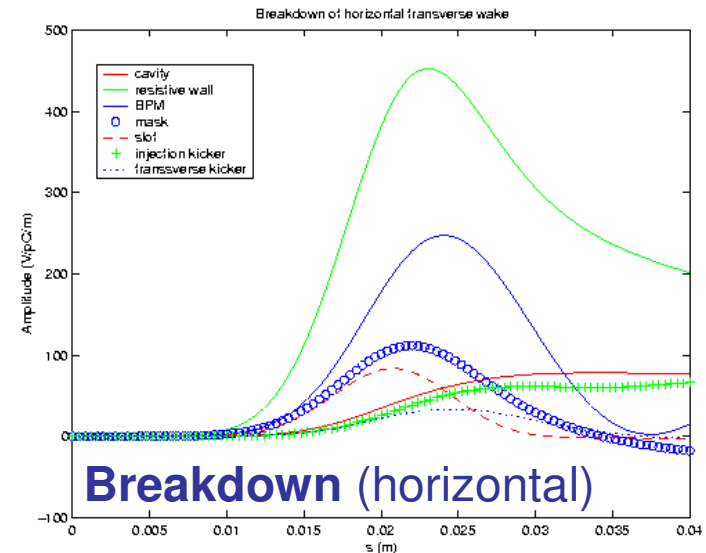
Impedance budget

| Component | Quantity | Horizontal kick factor (V/pC/m) | Vertical kick factor (V/pC/m) |
|-------------------|----------|---------------------------------|-------------------------------|
| RF Cavity | 3 | 36.08 | 36.08 |
| BPM | 159 | 146.76 | 146.76 |
| Slot | 102 | 56.34 | 0.13 |
| Mask | 102 | 77.01 | 1.22 |
| Injection kicker | 2 | 25.40 | 2.86 |
| Transverse kicker | 2 | 19.05 | 0.40 |
| Resistive wall | | 320.04 | 320.04 |
| Total | | 681 | 508 |

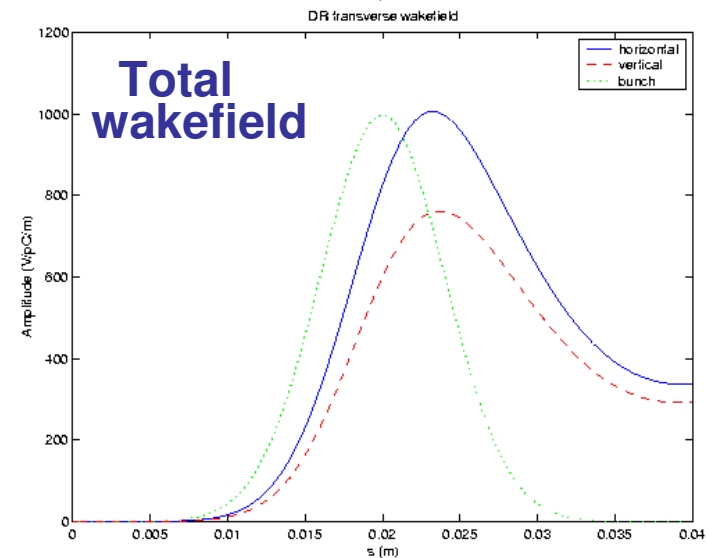
- dominated by resistive wall $\sim 1/b^3$:

$$W_1(s) = \frac{L}{b^3 \sigma_z^{1/2}} \frac{c}{2\pi} \sqrt{\frac{Z_0}{2\sigma_c}} f\left(\frac{s}{\sigma_z}\right)$$

$$f(u) = |u|^{1/2} e^{-u^2/4} (I_{-1/4} \pm I_{1/4})|_{u^2/4}$$



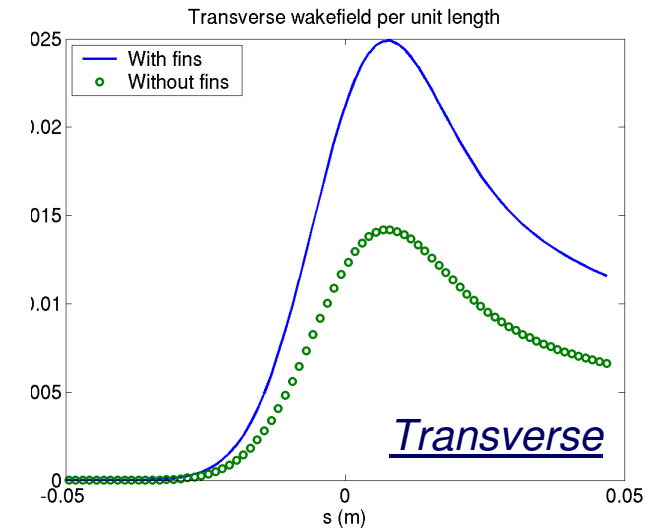
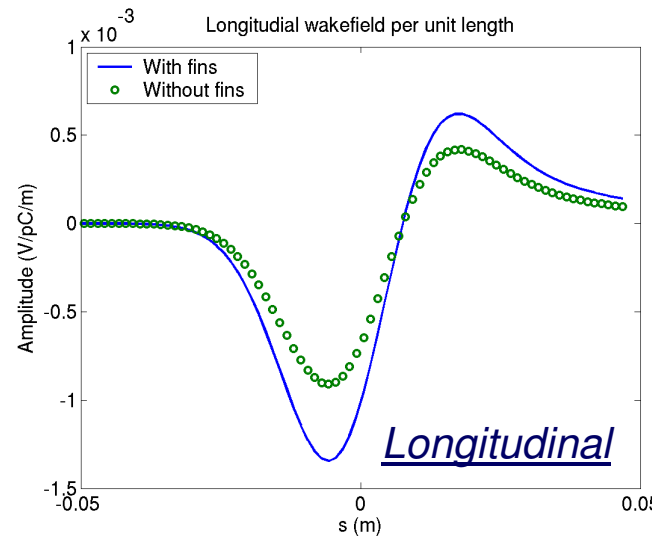
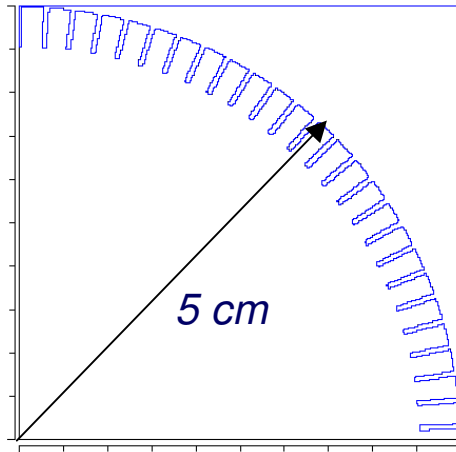
Breakdown (horizontal)



Total wakefield

Resistive Wall Wakefield (MAFIA)

MAFIA model



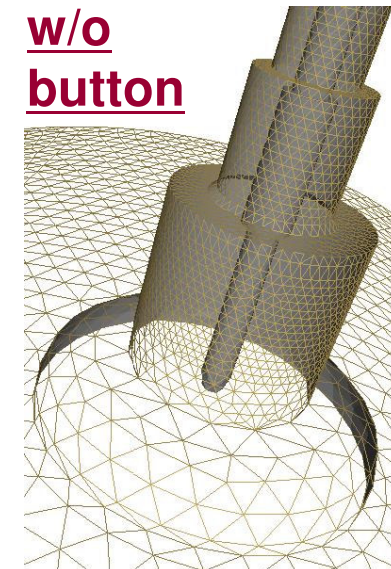
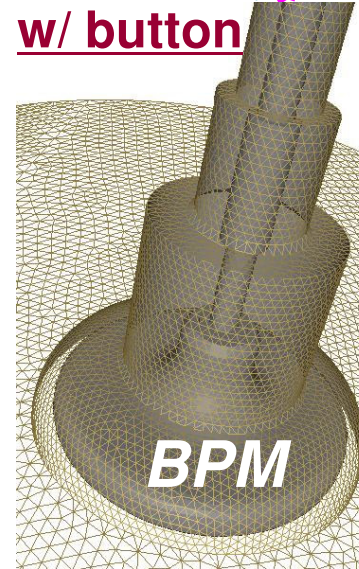
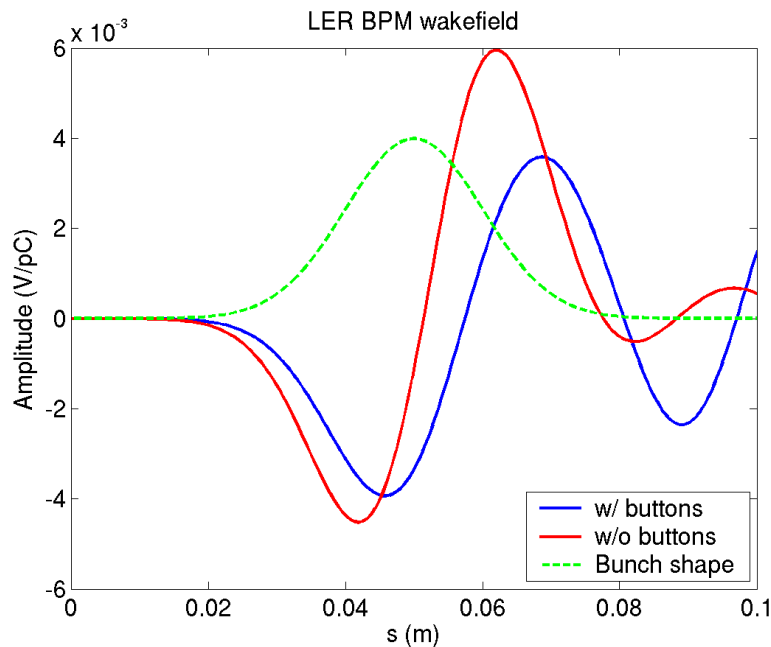
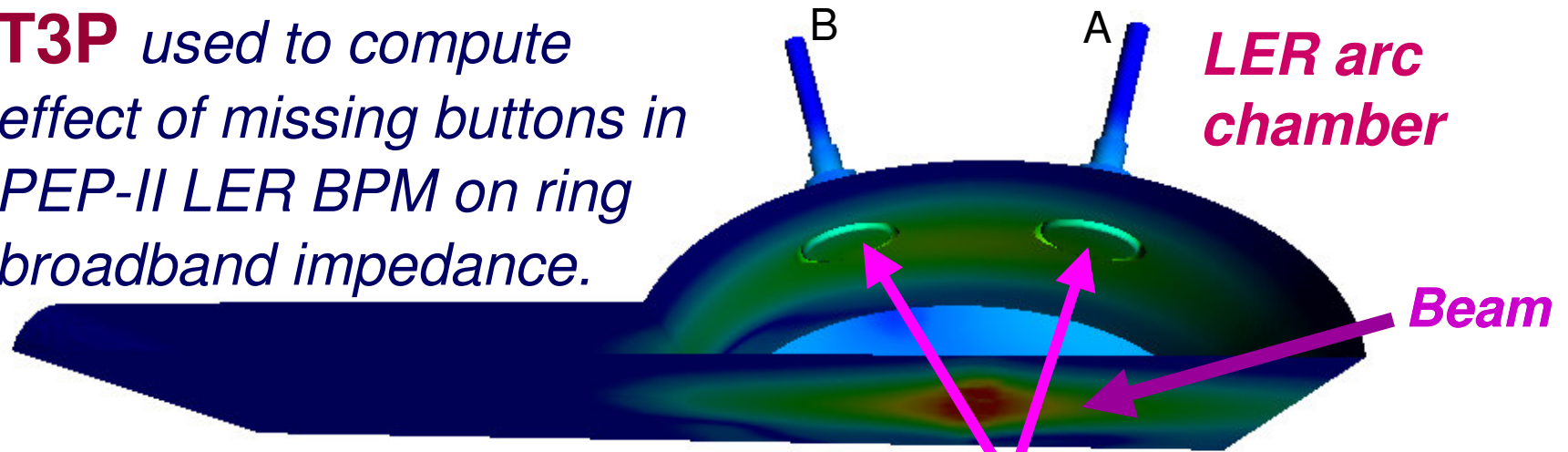
Longitudinal loss factor and transverse kick factor per unit length

| Wakefield | Smooth chamber | Chamber with fins |
|------------------------|----------------------|----------------------|
| Loss factor (V/pC/m) | 5.0×10^{-4} | 7.4×10^{-4} |
| Kick factor (V/pC/m/m) | 0.0090 | 0.016 |

Surface impedance boundary condition in T3P will provide better geometry resolution of grooved vacuum chamber of any cross section.

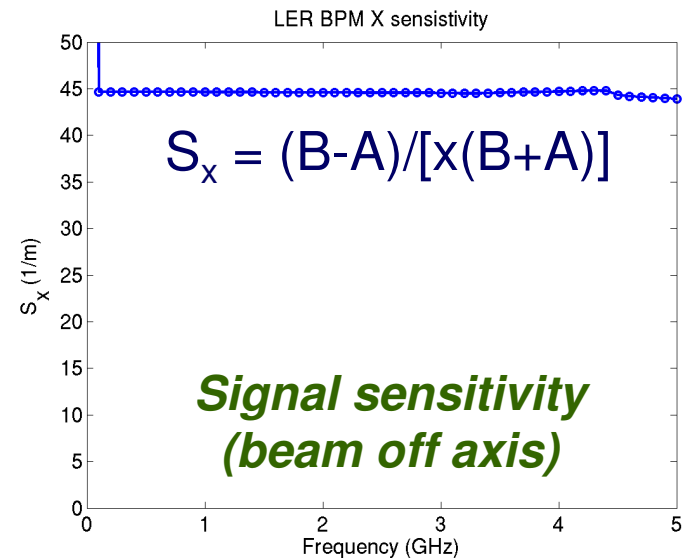
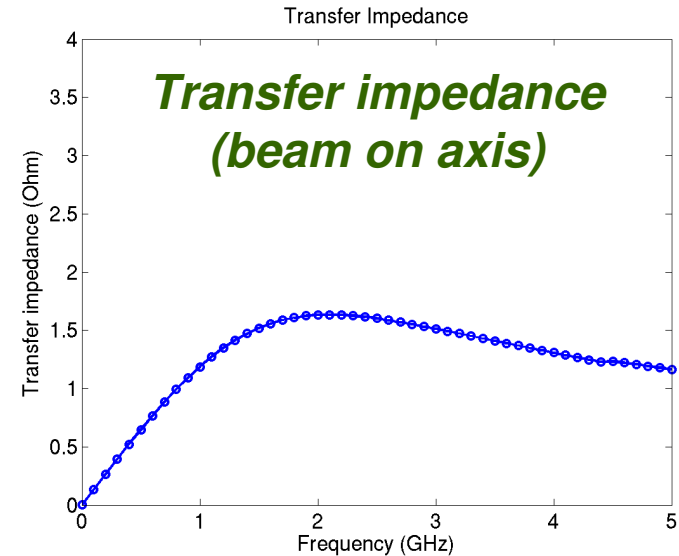
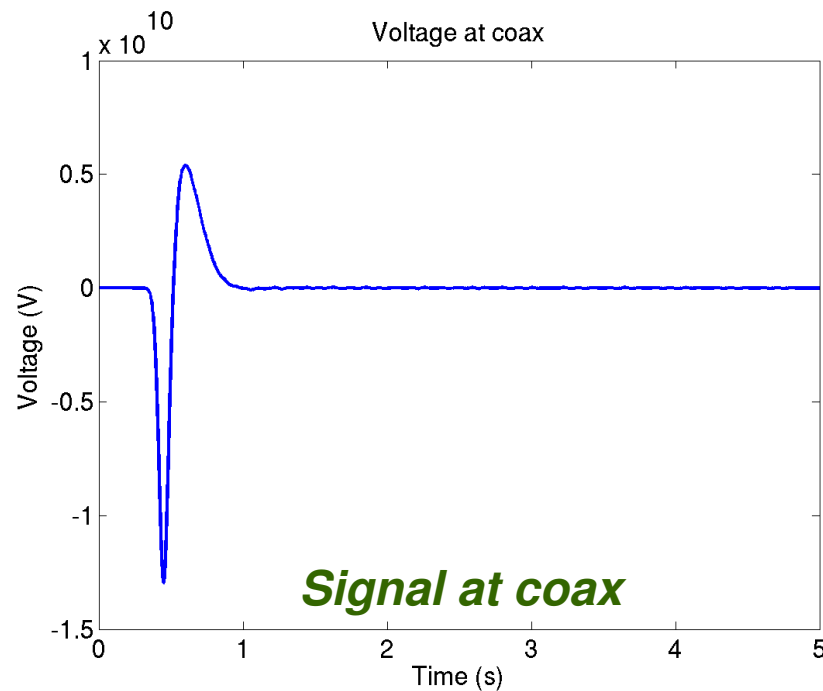
PEP-II LER BPM - Broadband Impedance

T3P used to compute effect of missing buttons in PEP-II LER BPM on ring broadband impedance.



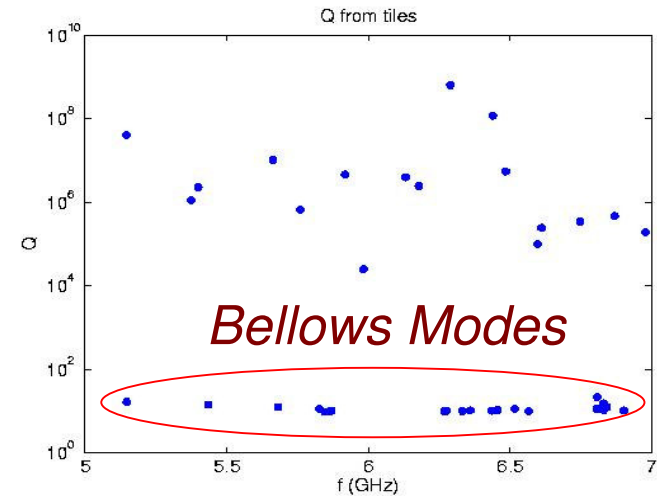
PEP-II LER BPM – Signal Sensitivity

Beam excited signals at the feedthroughs determine the transfer impedance and signal sensitivity.

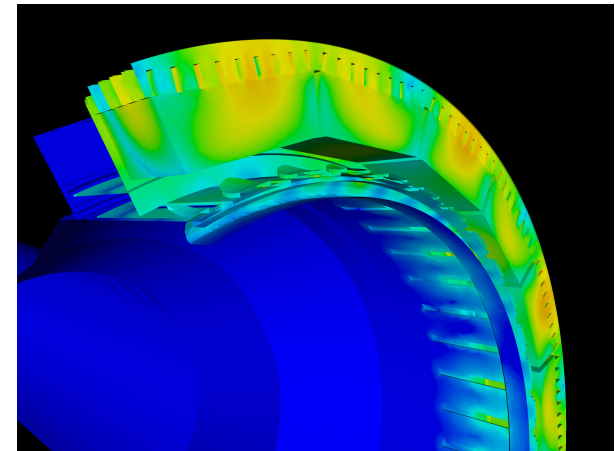
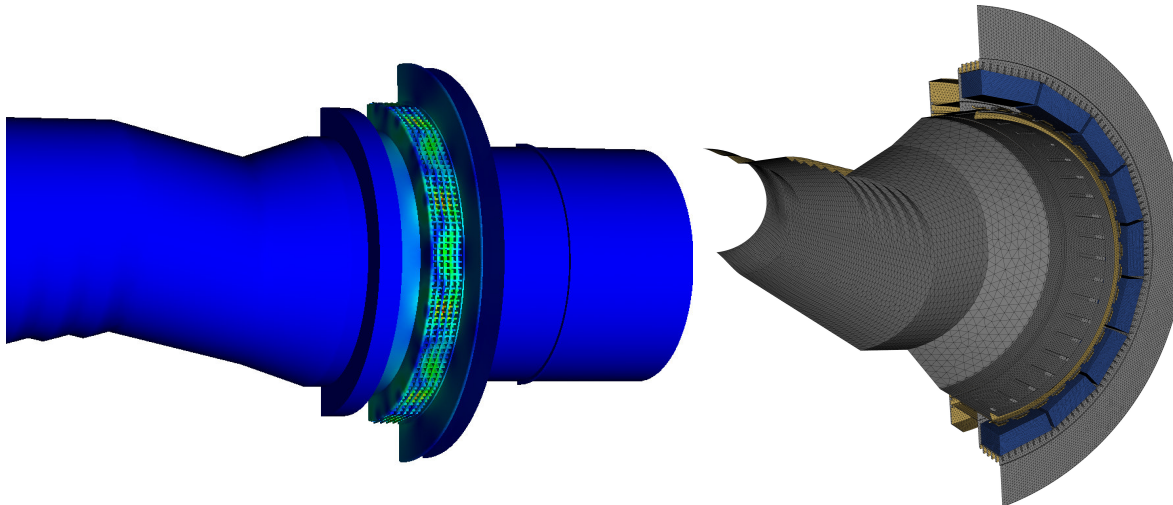


PEP-II Vertex Bellows Heating

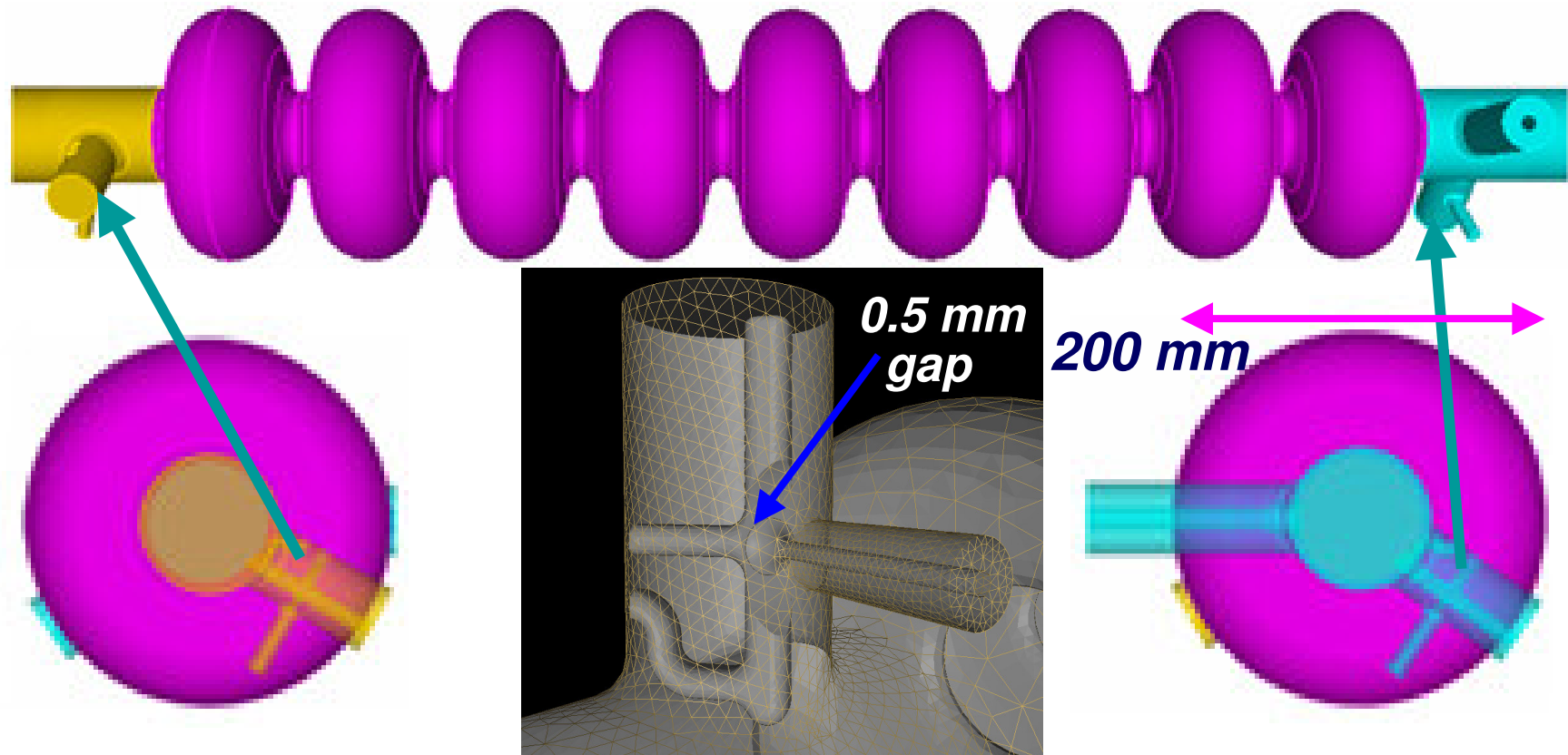
Omega3P was used to evaluate the damping of localized modes by ceramic tiles mounted on the bellows convolution. Bellows modes were found to be damped to very low Q s.



Bellows mode Ceramic tile absorber Dielectric loss

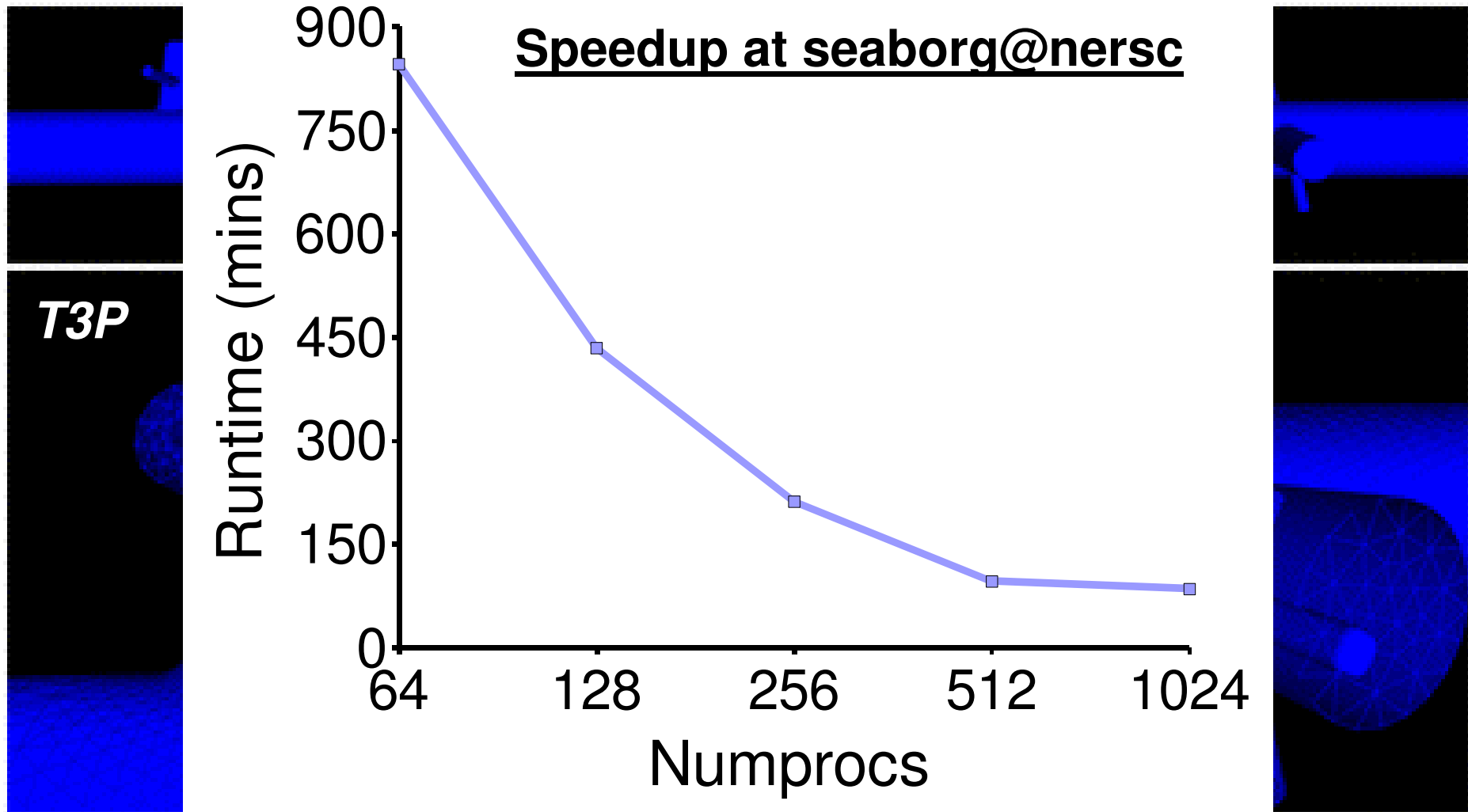


High Fidelity Modeling of TDR Cavity



- **Complexity** – HOM coupler (fine features) versus cell
- **Problem size** – multi-cavity structure, e.g. cryomodule
- **Accuracy** – 10's kHz mode separation out of GHz
- **Speed** – Fast turn around time to impact designs

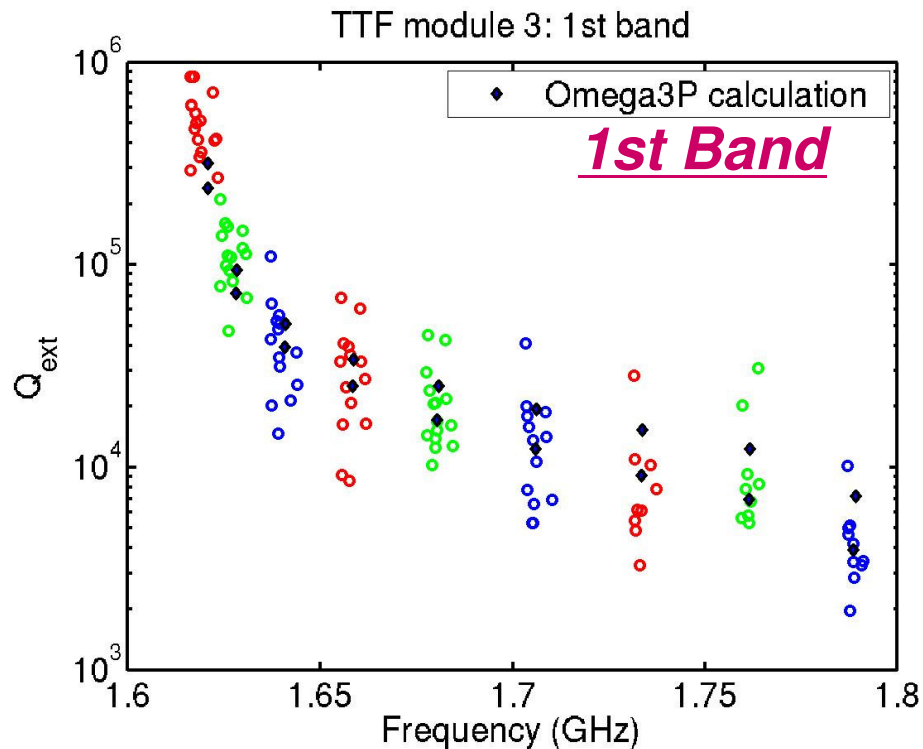
TDR Cavity – Wakefields (T3P)



1.75 M quadratic elements, 10 M DOFs, 47 min per nsec on Seaborg 1024 CPU with 173 GB memory – CG and incomplete Cholesky preconditioner

TDR Cavity – HOM Damping (Omega3P)

Comparison measurements (color) with **Omega3P** (black) complex eigenmode solutions ($Q_e = f_{real} / 2f_{imag}$)



0.53 M quadratic elements, 3.5 M DOFs, 512 CPU with 300 GB on Seaborg, Second Arnoldi with MUMPs, 1 hour per dipole band

Omega3P/T3P comparison

